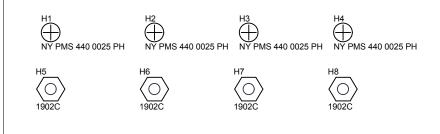


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Rev: 2	Project Title: LM53603 2-Layer TEXAS	
	Assembly Variant: [No Variations]       Sheet: 1 of 2       Instructional (No Neurophysical States)         File: PMP10604 rev2.SchDoc       Size: B       http://www.ti.com         Contact: http://www.ti.com/support       © Texas Instruments 2014	
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PCB Number: PMP10604 PCB Rev: A

PCB LOGO PCB LOGO Pb-Free Symbol Texas Instruments

ZZ1 Label Assembly Note This Assembly Note is for PCB labels only

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ZZ2 Assembly Note These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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